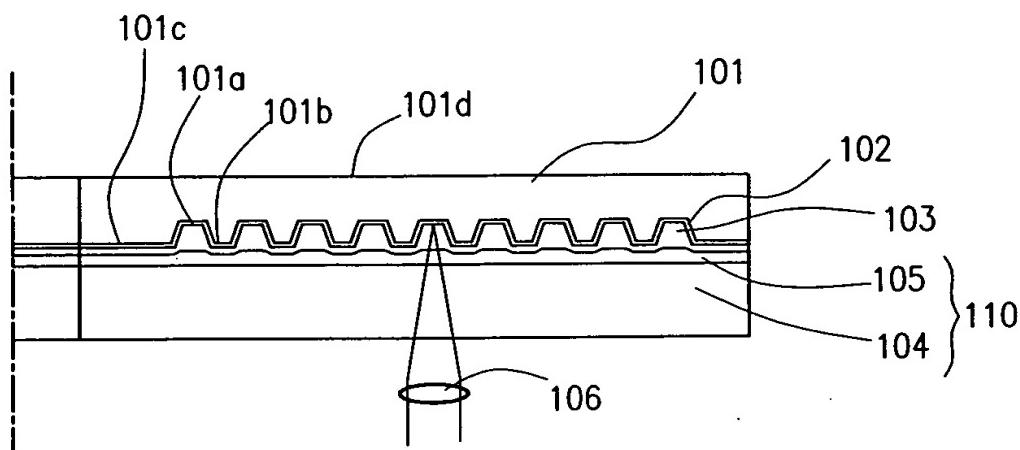
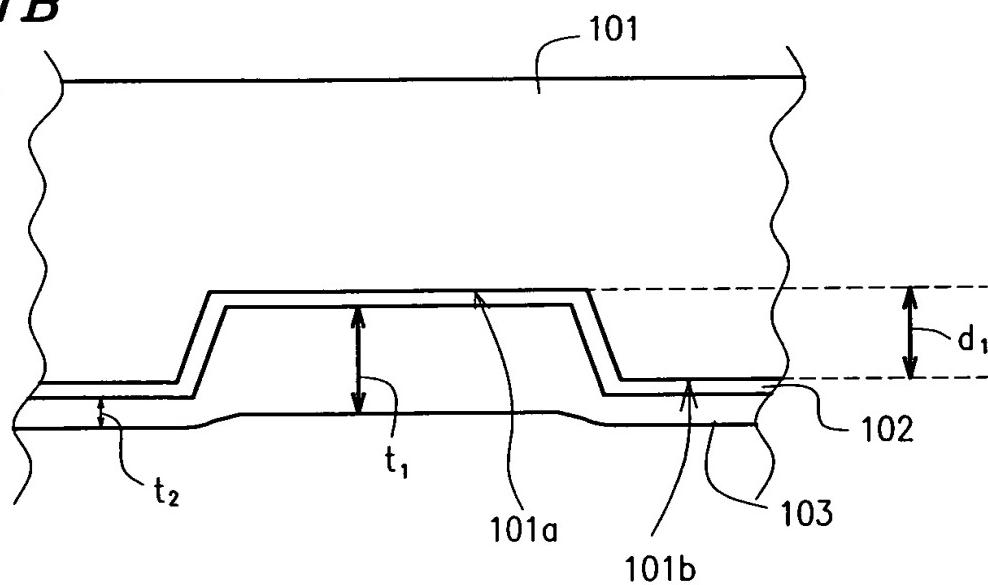




**FIG. 1A**

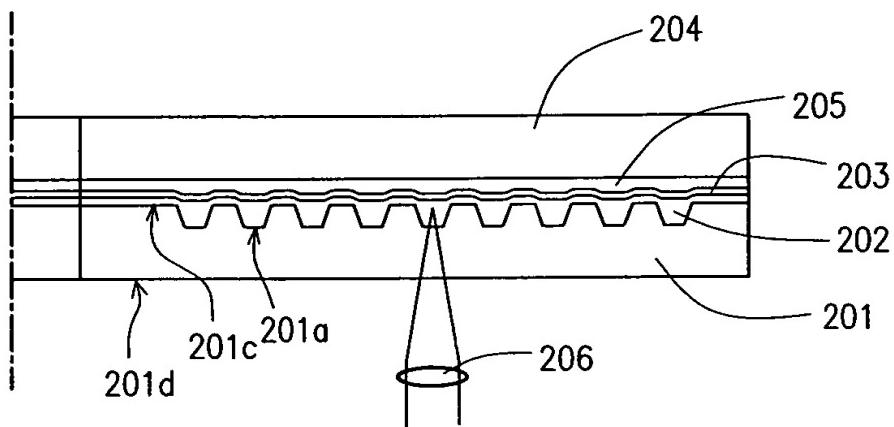


**FIG. 1B**

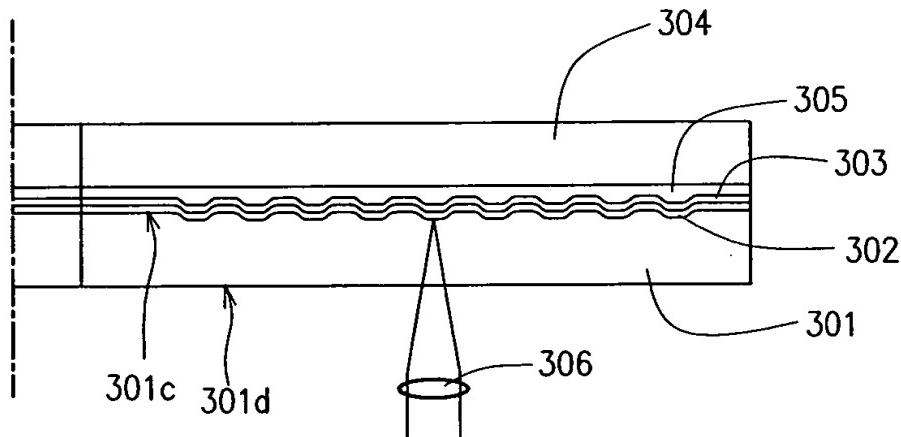


TOKYO 2020 OLYMPIC GAMES

**FIG.2**



**FIG.3**

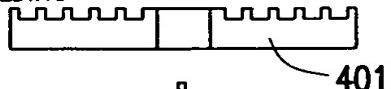


F04260 = EEE29660

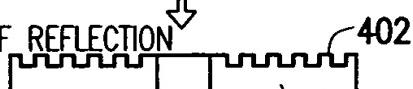
**FIG. 4**

FABRICATION STEP OF  
FIRST SUBSTRATE

(a) INJECTION MOLDING



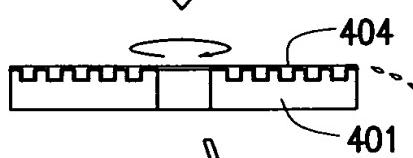
(b) SPUTTERING OF REFLECTION  
LAYER



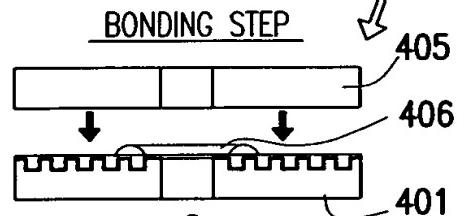
(c) APPLICATION OF RECORDING  
MATERIAL



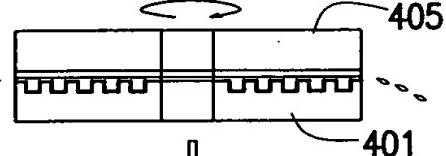
(d) SPIN COATING



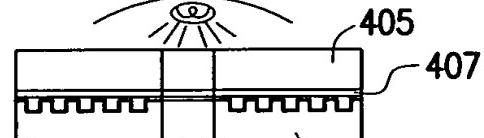
(f) APPLICATION OF ULTRAVIOLET  
RADIATION CURING RESIN,  
AND SUPERPOSING



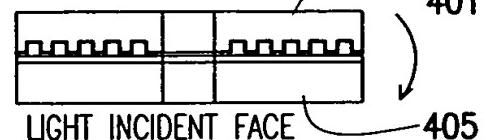
(g) SPIN BONDING



(h) CURING BY APPLICATION OF  
ULTRAVIOLET RADIATION



(i)



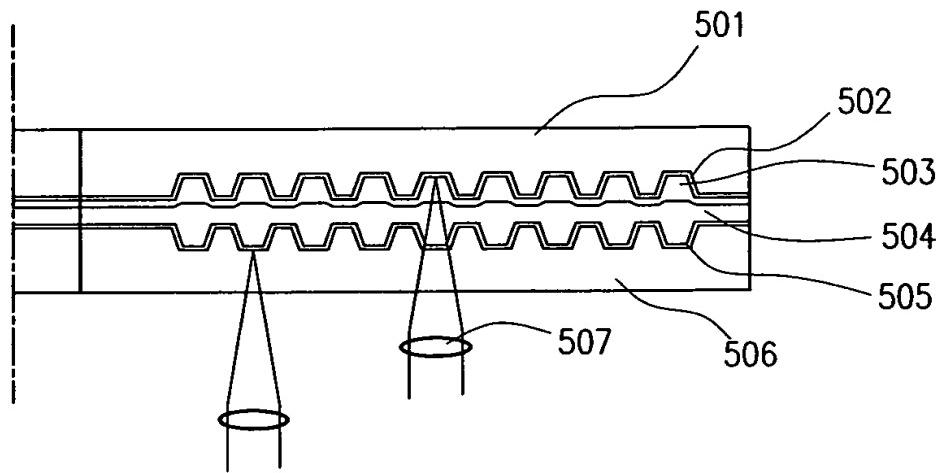
FABRICATION STEP OF  
SECOND SUBSTRATE

(e) INJECTION MOLDING



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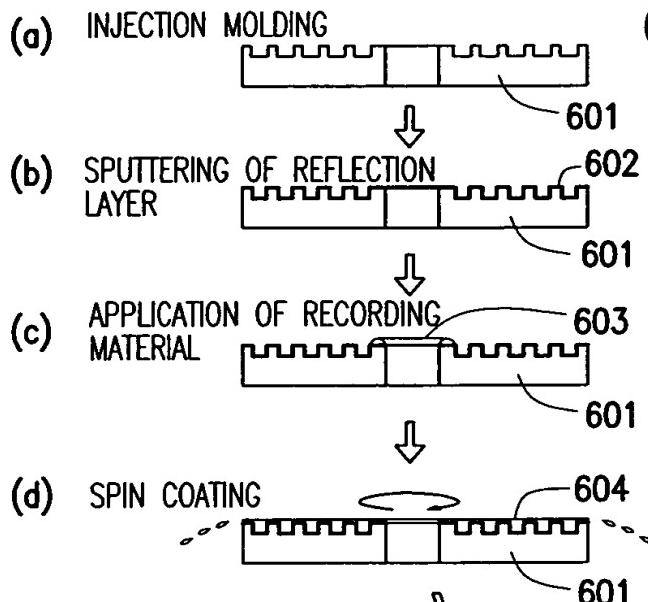
**FIG. 5**



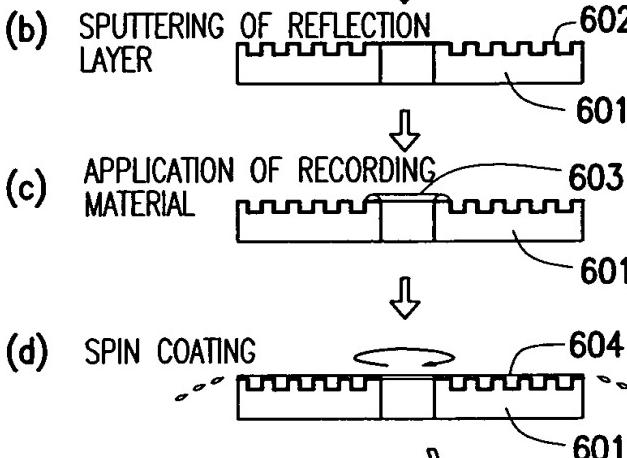
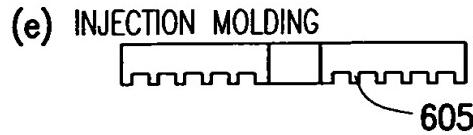
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**FIG. 6**

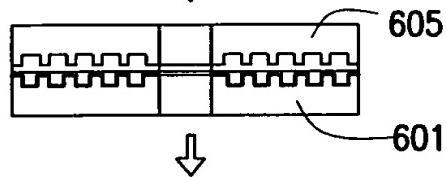
FABRICATION STEP OF  
FIRST SUBSTRATE



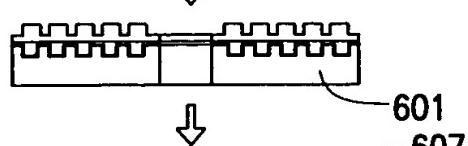
FABRICATION STEP OF  
SECOND SUBSTRATE



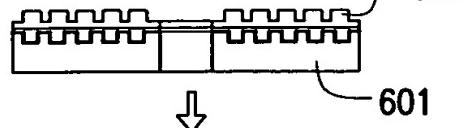
(g) SPIN BONDING



(h) PEELING



(i) FORMATION OF SEMITRANSPARENT FILM



(j) FORMATION OF TRANSPARENT COVER LAYER

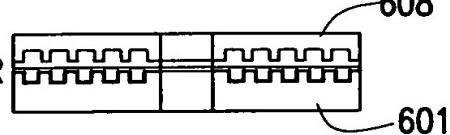
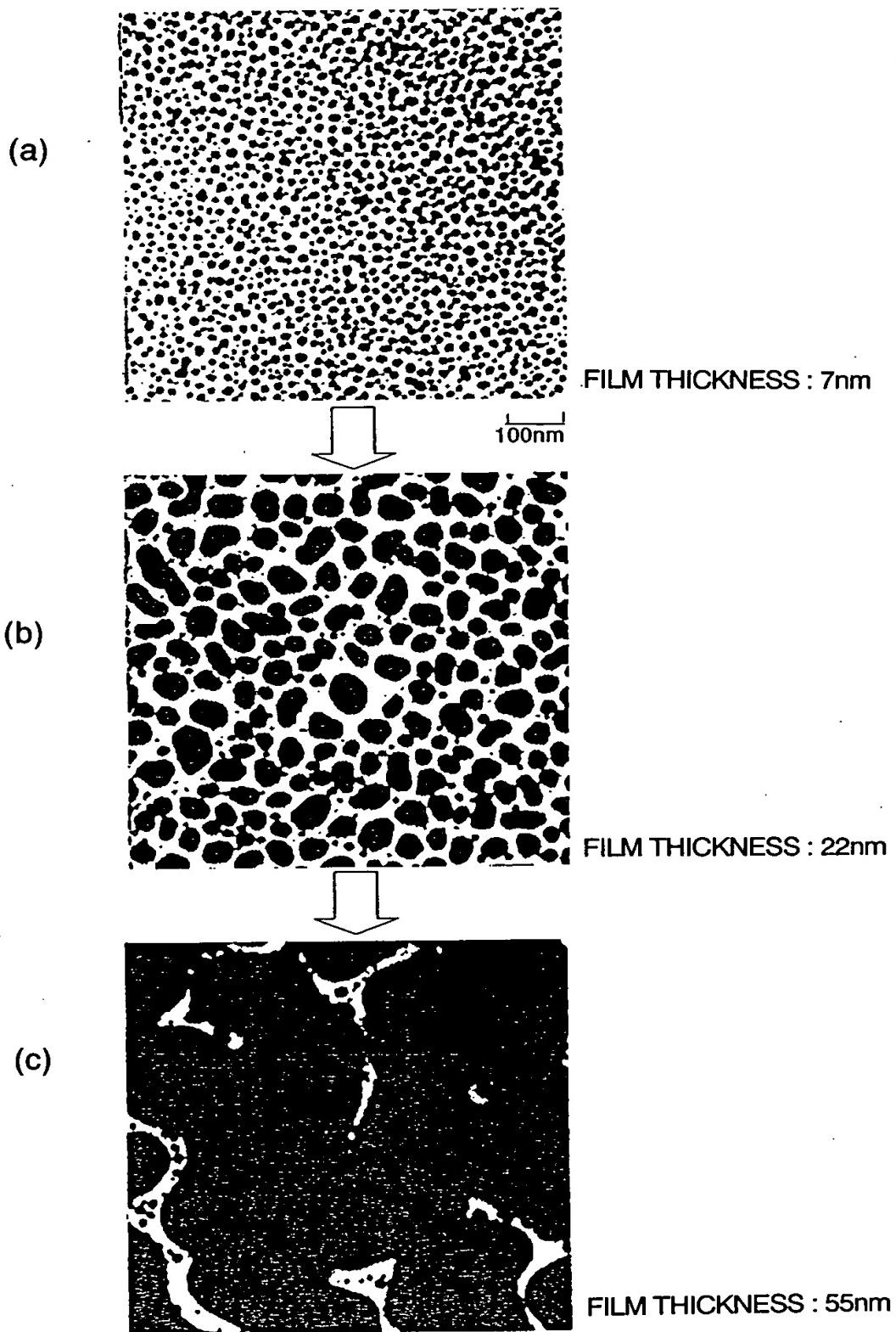


FIG. 7



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